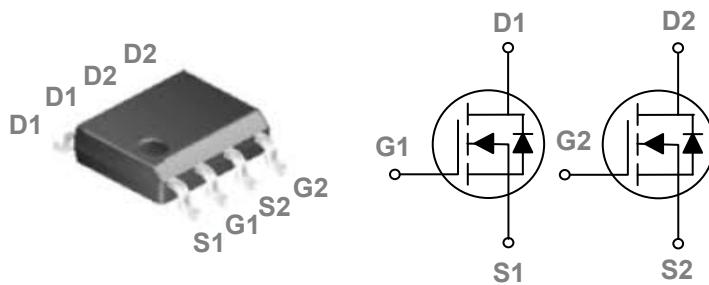


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOP8 Dual Pin Configuration



BVDSS	RDS(ON)	ID
60V	54mΩ	4.5A

### Features

- 60V, 4.5A, RDS(ON) = 54mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	4.5	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	2.85	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	18	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	11.25	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	15	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	2.1	W
	Power Dissipation – Derate above 25°C	0.017	W/°C
$T_{STG}$	Storage Temperature Range	-50 to 150	°C
$T_J$	Operating Junction Temperature Range	-50 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	60	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.07	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=5\text{A}$	---	44	54	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=3\text{A}$	---	50	63	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.2	1.8	2.5	V
			---	-4.2	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=10\text{A}$	---	6.5	---	S

**Dynamic and switching Characteristics**

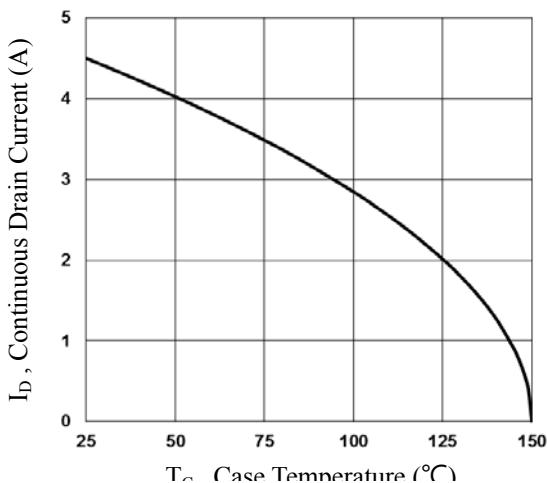
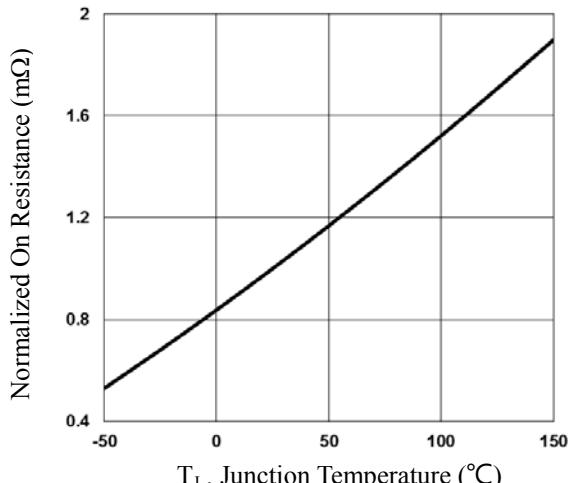
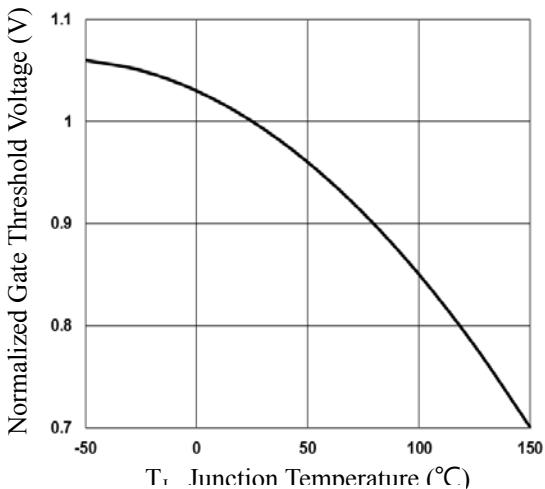
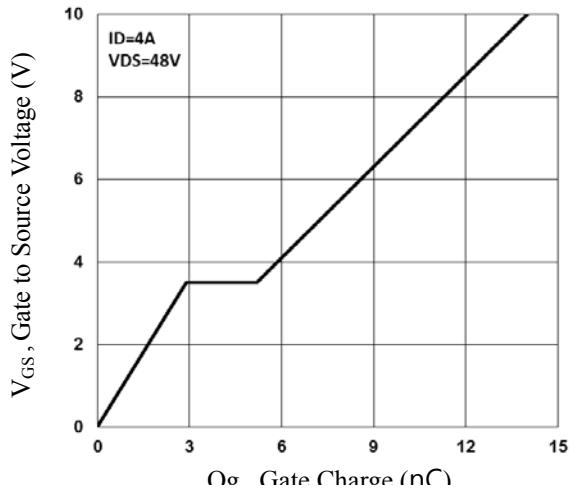
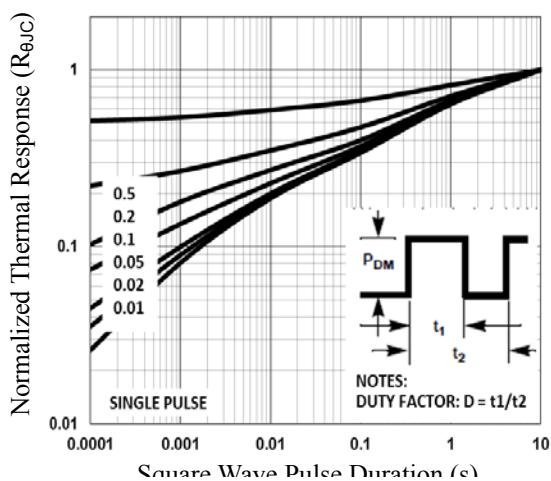
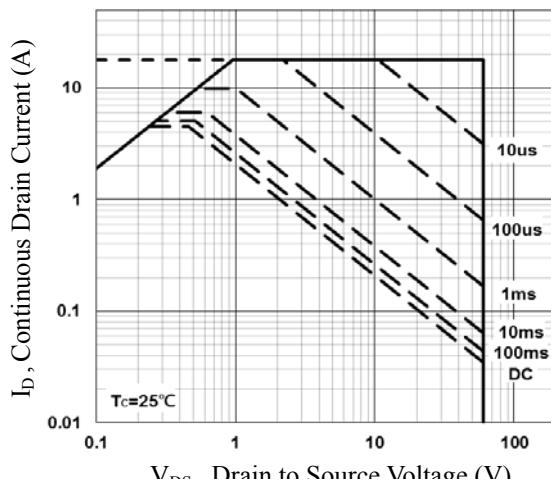
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=4\text{A}$	---	14	21	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	2.9	5	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	2.4	4	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$ $I_D=4\text{A}$	---	14	27	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	4	8	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	32	60	
$T_f$	Fall Time <sup>3, 4</sup>		---	2	4	
$C_{\text{iss}}$	Input Capacitance		---	835	1300	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	69	130	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	40	80	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	1.7	3.4	$\Omega$

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	4.5	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	9	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	---	14.6	28	ns
$Q_{\text{rr}}$	Reverse Recovery Charge <sup>3</sup>	$T_J=25^\circ\text{C}$	---	6.6	15	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=15\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1** Continuous Drain Current vs.  $T_C$ 

**Fig.2** Normalized RD<sub>SON</sub> vs.  $T_J$ 

**Fig.3** Normalized  $V_{th}$  vs.  $T_J$ 

**Fig.4** Gate Charge Waveform

**Fig.5** Normalized Transient Impedance

**Fig.6** Maximum Safe Operation Area

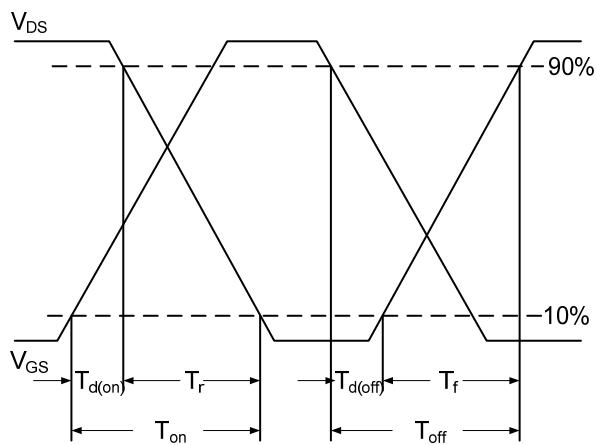


Fig.7 Switching Time Waveform

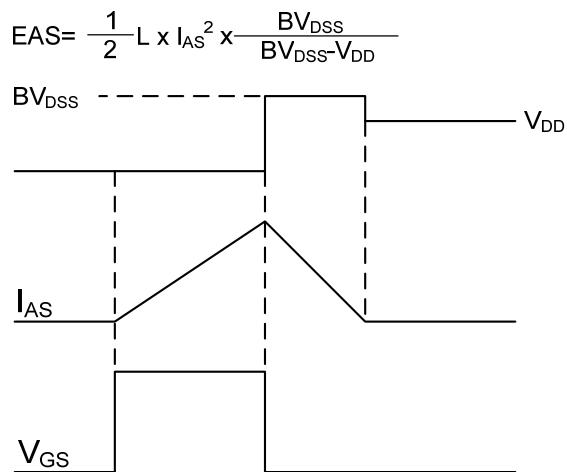
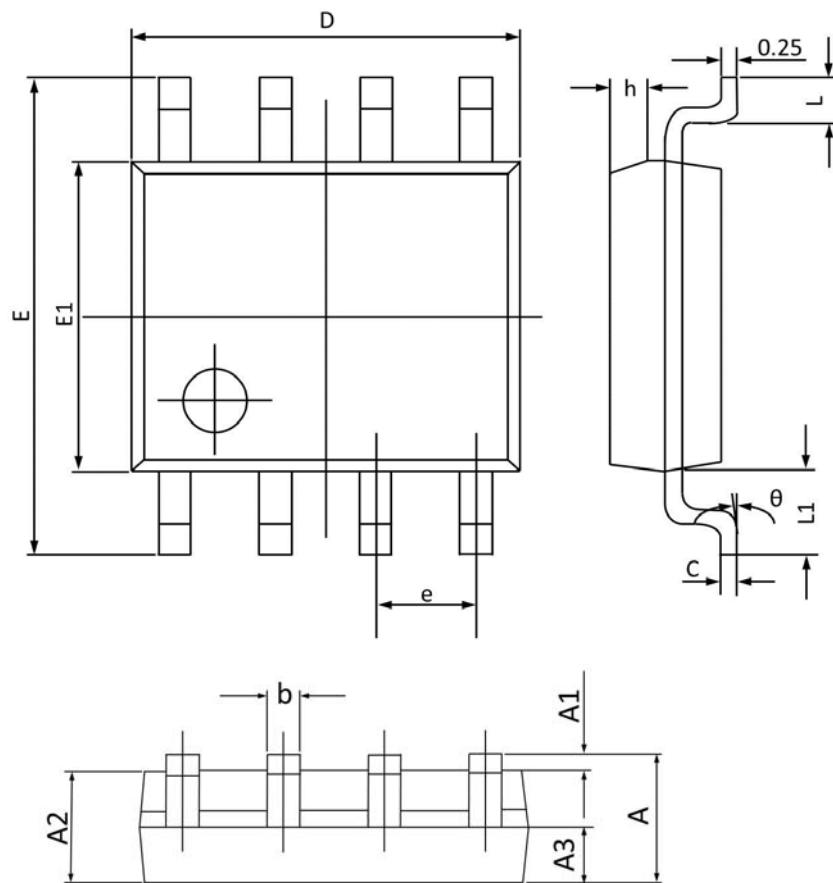


Fig.8 EAS Waveform

## SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.068
A1	0.100	0.250	0.004	0.009
A2	1.300	1.500	0.052	0.059
A3	0.600	0.700	0.024	0.027
b	0.390	0.480	0.016	0.018
c	0.210	0.260	0.009	0.010
D	4.700	5.100	0.186	0.200
E	5.800	6.200	0.229	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.019
L	0.500	0.800	0.019	0.031
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°